TOSHIBA 2SJ509

TOSHIBA FIELD EFFECT TRANSISTOR SILICON P CHANNEL MOS TYPE (L2-π-MOS V)

2 S J 5 0 9

HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE **APPLICATIONS**

- 4 V Gate Drive
- Low Drain-Source ON Resistance : $R_{DS(ON)} = 1.35 \Omega$ (Typ.)
- High Forward Transfer Admittance: $|Y_{fs}| = 0.7 \,\mathrm{S}$ (Typ.)
- Low Leakage Current

:
$$I_{DSS} = -100 \,\mu\text{A} \,(V_{DS} = -100 \,\text{V})$$

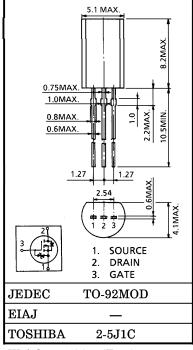
Enhancement-Mode

:
$$V_{th} = -0.8 \sim -2.0 \text{ V (V}_{DS} = -10 \text{ V, I}_{D} = -1 \text{ mA)}$$

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERIS	SYMBOL	RATING	UNIT	
Drain-Source Voltage	$v_{ m DSS}$	-100	V	
Drain-Gate Voltage (R _{GS} = $20 \text{ k}\Omega$)		$v_{ m DGR}$	-100	V
Gate-Source Voltage		v_{GSS}	±20	V
Drain Current	DC	I_{D}	-1	A
	Pulse	I_{DP}	-3	A
Drain Power Dissipation (Ta = 25°C)	PD	0.9	w	
Single Pulse Avalanche Energy**		EAS	136.5	mJ
Avalanche Current	I_{AR}	-1	Α	
Repetitive Avalanche En	E_{AR}	0.09	mJ	
Channel Temperature	$\mathrm{T_{ch}}$	150	$^{\circ}\mathrm{C}$	
Storage Temperature Range		$\mathrm{T_{stg}}$	-55~150	°C

INDUSTRIAL APPLICATIONS Unit in mm



Weight: 0.36 g (Typ.)

THERMAL CHARACTERISTICS

	SYMBOL		UNIT
Thermal Resistance, Channel to Ambient	R _{th (ch-a)}	138	°C/W

Note:

- Repetitive rating; Pulse Width Limited by Max. junction temperature.
- $V_{DD} = -50 \text{ V}$, Starting $T_{ch} = 25^{\circ}\text{C}$, L = 168 mH, $R_G = 25 \Omega$, $I_{AR} = -1 \text{ A}$

This transistor is an electrostatic sensitive device. Please handle with caution.

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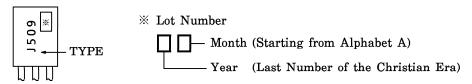
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARA	CTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage	e Current	I_{GSS}	$V_{GS} = \pm 16 V, \ V_{DS} = 0 V$		_	±10	μ A
Drain Cut-off	Current	$I_{ m DSS}$	$V_{DS} = -100 V, V_{GS} = 0 V$	-	_	-100	μ A
Drain-Source Voltage	Breakdown	V _(BR) DSS	$I_{ m D} = -10 { m mA}, \; { m V}_{ m GS} = 0 { m V}$	-100		_	v
Gate Thresho	ld Voltage	$ m V_{th}$	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$	-0.8	_	-2.0	V
Drain-Source	ON Resistance	R _{DS} (ON)	$V_{GS} = -4 \text{ V}, I_{D} = -0.5 \text{ A}$ $V_{GS} = -10 \text{ V}, I_{D} = -0.5 \text{ A}$		1.68 1.34	2.5 1.9	Ω
Forward Tran Admittance	nsfer	$ Y_{fs} $	$V_{ m DS} = -10 m V, I_{ m D} = -0.5 m A$	0.3	0.7	_	S
Input Capaci	tance	$\mathrm{c}_{\mathrm{iss}}$			135	_	
Reverse Tran Capacitance	sfer	$\mathrm{C}_{ extbf{rss}}$	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz	1	22	_	рF
Output Capacitance		Coss		_	48	_	
Switching Time Fa	Rise Time	t _r	V_{GS} V_{OUT} V_{OUT} V_{OUT}	1	20	_	
	Turn-on Time	ton	$V_{GS} = 10 \text{ V}$ $V_{GS} = 10 \text{ V}$ $V_{DD} = -50 \text{ V}$		32	_	ns
	Fall Time	t_f		_	25	_	
	Turn-off Time	^t off	$V_{\mathrm{IN}}: \mathrm{t_r}, \mathrm{t_f} < 5 \mathrm{ns},$ Duty $\leq 1\%, \mathrm{t_W} = 10 \mu \mathrm{s}$	1	130	_	
Total Gate Charge (Gate-Source Plus Gate-Drain)		$\mathbf{Q}_{\mathbf{g}}$	$V_{DD} = -80 \text{ V}, V_{GS} = -10 \text{ V},$		6.3	_	~C
Gate-Source Charge		$Q_{ m gs}$	$I_{\rm D} = -1 {\rm A}$		4.1	_	nC
Gate-Drain ("Miller") Charge		$ m Q_{gd}$		_	2.2	_	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	$I_{ m DR}$	_	_	_	-1	A
Pulse Drain Reverse Current	$I_{ m DRP}$	_	_	_	-3	A
Diode Forward Voltage	${ m v_{DSF}}$	$I_{DR} = -1 A$, $V_{GS} = 0 V$	_	_	1.5	V
Reverse Recovery Time	${ m t_{rr}}$	$I_{DR} = -1 A$, $V_{GS} = 0 V$		90	_	ns
Reverse Recovery Charge	Q_{rr}	$dI_{DR}/dt = 50 A/\mu s$	_	180	_	nC

MARKING



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